1   199   heat adj sink near5 silicone	L Number	Hits	Search Text	DB	Time stamp
2   78   sheet and (heat adj sink near5 silicone)   EPO; JPO; DERWENT; IBM TIDB   USPAT; US-PGFUB; EPO; JPO; DERWENT; IBM TIDB   USPAT;		199	heat adj sink near5 silicone	USPAT;	2004/06/03
2		'	-	US-PGPUB;	10:16
Tem Type   2004/06/03   10:14   10:16   10:1					
2					
1014	_	7.0			0004/06/03
SEPO, JPO, DERWENT; IBM TDB   10:16	4	/8	sheet and (heat ad) sink hears silicone)		1
3					10.14
140   (257/625).CCLS.					
10:16				1	
Total	3	140	(257/625).CCLS.	USPĀT;	2004/06/03
### Top				1	10:16
The TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWEN					,
4 747 (257/675).CCLS.				1	
S   S   S   S   S   S   S   S   S   S	4	747	(257/675) CCI.S	_	2004/06/03
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT, IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; I	]		(2077 0707 100251		1 ' '
S   308796   silicone     IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM TDB   USPAT;   U					
2004/06/03   10:17   10:5   10:17   10:5   10:17   1	]				
US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWE				_	
BPO, JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; US-PGPUB; EPO, JPO; DE	5	308796	silicone		1
DERWENT; IBM TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB   USPAT;				1	10:1/
Section   Sect				1	
Continue					
10:30	6	77	((257/675).CCLS.) and silicone	_	2004/06/03
Tolar   Derment   Dermen				US-PGPUB;	10:30
TIM TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-				1	
7 759 257/E23.101					
S	,	750	257/E22 101	_	2004/06/03
EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; USPGPUB; EPO; JPO; DERWENT; ISM_TDB   USPAT; USPGPUB; EPO; JPO; DERWENT; ISM_TDB   USPAT; USPGPUB; EPO; JPO; DERWENT; EPO; JPO; DERWENT; ISM_TDB   USPAT; USPGPUB; EPO; JPO; DERWENT;	′	759	237/623.101		
B					10.33
8 83 silicone and 257/E23.101 USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; DERWENT; DERWENT; DERWENT;				1 '	
Second				IBM_TDB	
Second	8	83	silicone and 257/E23.101	1 '	
DERWENT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT;				1	10:30
ST   ST   ST   ST   ST   ST   ST   ST				1 '	
9 357 257/E23.107 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; J			·		
EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; USPAT; US-	9	357	257/E23.107		2004/06/03
DERWENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;				US-PGPUB;	10:37
IBM_TDB	]				
10	]				
1	10	157			2004/06/03
EPO; JPO; DERWENT; IBM_TDB	10	137	3111Cone and 23//823.10/		
DERWENT;   IBM_TDB   USPAT;   US-PGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;   USPAT;   USPAT;   USPAT;   USPAT;   USPGPUB;   EPO; JPO;   DERWENT;   IBM_TDB   USPAT;	]				''''
1				DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT					
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPGPUB; EPO; JPO; DERWENT; USPGPUB; EPO; JPO; DERWENT;	11	39	257/E23.108		
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US	]			1	10:37
lucent and lishner.in.    IBM_TDB_USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPGPUB; EPO; JPO; DERWENT; USPGPUB; EPO; JPO; DERWENT;					.
- 1 lucent and lishner.in.  1 lucent and lishner.in.  2004/01/28 12:30  1 USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; USP				-	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB  (heat adj sink or heatsink or heat adj dissipation) and (flipchip or flip adj chip) and planar  US-PGPUB; EPO; JPO; DERWENT; 2004/01/28  US-PGPUB; EPO; JPO; DERWENT;	_	1	lucent and lishner.in.		2004/01/28
DERWENT; IBM_TDB USPAT; dissipator or heat adj dissipation) and (flipchip or flip adj chip) and planar  DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;				US-PGPUB;	12:30
- 871 (heat adj sink or heatsink or heat adj dissipation) and (flipchip or flip adj chip) and planar (flipchip or flip adj chip) and planar (DERWENT;					
- 871 (heat adj sink or heatsink or heat adj dissipation) and (flipchip or flip adj chip) and planar (flipchip or flip adj chip) and planar (berwent; 2004/01/28 12:31 EPO; JPO; DERWENT;				1	]
dissipator or heat adj dissipation) and US-PGPUB; 12:31 (flipchip or flip adj chip) and planar EPO; JPO; DERWENT;	[_	971	(heat add sink or heateink or heat add		2004/01/28
(flipchip or flip adj chip) and planar EPO; JPO; DERWENT;		0,1			
DERWENT;					
I I GOOD MOST				DERWENT;	
! ! - !				IBM_TDB	
- 112 orthogonal and ((heat adj sink or USPAT; 2004/01/28	-	112			1
heatsink or heat adj dissipator or heat US-PGPUB; 12:38 adj dissipation) and (flipchip or flip EPO; JPO;				l ·	12:38
adj dissipation) and (Hipchip of Hip   EPO; JPO;   adj chip) and planar)   DERWENT;				1	
IBM TDB		1	and only and planal		<u> </u>

-	19	5001548.URPN.	USPAT	2004/01/28
_	214	silicone and ((heat adj sink or heatsink or heat adj dissipator or heat adj dissipation) and (flipchip or flip adj chip) and planar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	12:36 2004/01/28 12:39